

Abstract

A conductive paste based on an elastomer of the polyoxypolyolefin type or on a member of the polyolefin family is described, provided with an admixture of
5 conductive particles for the production, in the electronics industry, of a sealing element, of a contact element or of a heat-conduction element. This material is particularly suitable for the production of EMI-RFI gaskets, and, compared with materials known
10 hitherto and based on silicone, has improved performance characteristics and environmental properties.

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